

Hyper A+ Server AS -2115HS-TNR

2U UP Hyper with 24 hot-swap 2.5" drive bays and 1 PCIe 5.0 slot



More details here

Key Applications

Virtualization, Software-defined Storage, AI Inference and Machine Learning, Cloud Computing, Enterprise Server,

Key Features

- Single AMD EPYC™ 9004/9005* Series Processor
(*AMD EPYC™ 9005 series drop-in support requires board revision 2.x);
- Support up to DDR5 24 DIMM slots (2DPC)
(Please check System Memory Section for detail);
- Optional PCIe slot configurations up to 8 PCIe 5.0 x8 or 4 PCIe 5.0 x16 slots or mix and match
Flexible networking options with 1 AIOM networking slot (OCP NIC 3.0 compatible);
- 24 Hot-swap 2.5" NVMe/SATA/SAS drive bays
2 M.2 PCIe 3.0 NVMe slots;
- Dual 1600W Redundant Titanium Level power supplies
(Power supply full redundancy based on configuration and application load);



Form Factor	2U Enclosure: 437 x 88.9 x 760mm (17.2" x 3.5" x 29.9") Package: 605 x 263 x 1107mm (23.8" x 10.4" x 43.6")
Processor	Single processor(s) AMD EPYC™ 9004/9005 Series Processors (* AMD EPYC™ 9005 Series drop-in support requires board revision 2.x) Up to 160C/320T
GPU	Max GPU Count: Up to 2 double-width GPUs Supported GPU: NVIDIA PCIe: RTX 6000 Ada Generation, RTX A6000 CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect GPU-GPU Interconnect: PCIe
System Memory	Slot Count: 24 DIMM slots Max Memory (1DPC): Up to 3TB 4800MT/s ECC DDR5 RDIMM (AMD EPYC™ 9004 Series Processor) Max Memory (2DPC): Up to 6TB 4000MT/s ECC DDR5 RDIMM (AMD EPYC™ 9004 Series Processor) Max Memory (1DPC): Up to 3TB 5200MT/s ECC DDR5 RDIMM (AMD EPYC™ 9005 Series Processor) Max Memory (2DPC): Up to 6TB 4400MT/s ECC DDR5 RDIMM (AMD EPYC™ 9005 Series Processor)
Drive Bays Configuration	Default: Total 24 bays • 24 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays (*NVMe/SAS/SATA support may require additional storage controller and/or cables) M.2: 1 M.2 PCIe 3.0 x4 NVMe slot (M-key 22110(default)/2280) 1 M.2 PCIe 3.0 x2 NVMe slot (M-key 22110(default)/2280)
Expansion Slots	Default • 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible) Option A* • 1 PCIe 5.0 x16 FHFL double-width slot • 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible) Option B* • 2 PCIe 5.0 x8 (in x16) FHFL slots • 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible) Option C* • 2 PCIe 5.0 x16 FHFL double-width slots • 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible) Option D* • 1 PCIe 5.0 x16 FHFL double-width slot • 2 PCIe 5.0 x8 (in x16) FHFL slots • 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)

- Option E*
- 4 PCIe 5.0 x8 (in x16) FHFL slots
 - 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)

- Option F*
- 4 PCIe 5.0 x16 FHFL double-width slots
 - 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)

- Option G*
- 3 PCIe 5.0 x16 FHFL double-width slots
 - 2 PCIe 5.0 x8 (in x16) FHFL slots
 - 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)

- Option H*
- 2 PCIe 5.0 x16 FHFL double-width slots
 - 4 PCIe 5.0 x8 (in x16) FHFL slots
 - 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)

- Option I*
- 1 PCIe 5.0 x16 FHFL double-width slot
 - 6 PCIe 5.0 x8 (in x16) FHFL slots
 - 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)

On-Board Devices	Chipset: System on Chip Network Connectivity: Via AIOM
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Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port USB: 2 USB 3.0 ports(rear) Video: 1 VGA port
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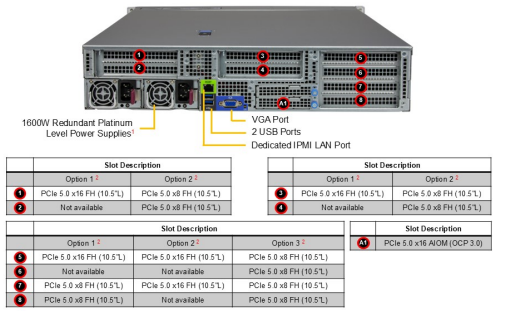
(Front View – System)



Drive Bay	Description
1 – 28	28 Hot-swap 2.5" NVMe/SAS/SATA Drive Bays ¹

¹ NVMe/SAS/SATA functionality depends on configuration chosen and may require additional parts from the optional parts kit

(Rear View – System)



Slot Description		Slot Description	
Option 1: ¹	Option 2: ¹	Option 1: ¹	Option 2: ¹
1 PCIe 5.0 x16 FH (10.5 L)	PCIe 5.0 x8 FH (10.5 L)	1 PCIe 5.0 x16 FH (10.5 L)	PCIe 5.0 x8 FH (10.5 L)
2 Not available	PCIe 5.0 x8 FH (10.5 L)	2 Not available	PCIe 5.0 x8 FH (10.5 L)

Slot Description		Slot Description	
Option 1: ¹	Option 2: ¹	Option 3: ¹	Option 4: ¹
1 PCIe 5.0 x16 FH (10.5 L)	PCIe 5.0 x16 FH (10.5 L)	PCIe 5.0 x8 FH (10.5 L)	PCIe 5.0 x8 FH (10.5 L)
2 Not available	Not available	PCIe 5.0 x8 FH (10.5 L)	PCIe 5.0 x8 FH (10.5 L)
3 PCIe 5.0 x8 FH (10.5 L)	PCIe 5.0 x16 FH (10.5 L)	PCIe 5.0 x8 FH (10.5 L)	PCIe 5.0 x8 FH (10.5 L)
4 PCIe 5.0 x8 FH (10.5 L)	Not available	PCIe 5.0 x8 FH (10.5 L)	PCIe 5.0 x8 FH (10.5 L)

¹ Full redundancy based on configuration and application load
² Slots 1, 2, 3, 4, 5, 6 are not available with 24 160W configuration
 Slots 3, 4, 5, 6 are not available with 28 160W configuration

System Cooling	Fans: Up to 4x 8cm heavy duty fans with optimal fan speed control Air Shroud: 1 Air Shroud
Power Supply	2x 1600W Redundant (1 + 1) Titanium Level (96%) power supplies
System BIOS	BIOS Type: AMI 32MB SPI Flash EEPROM BIOS Features: ACPI 6.4 Plug and Play (PnP) SMBIOS 3.5 or later UEFI 2.8 USB Keyboard support
Management	SuperCloud Composer®; Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); Supermicro SuperDoctor® 5 (SD5); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); OOB Management Package (SFT-OOB-LIC); SuperServer Automation Assistant (SAA) New!
PC Health Monitoring	FAN: Fans with tachometer monitoring Pulse Width Modulated (PWM) fan connectors Status monitor for speed control Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors Voltage: System temperature, Memory temperature, CPU temperature, 3.3V standby, +5V standby, +5V, +3.3V, +12V, CPU thermal trip support
Dimensions and Weight	Weight: Gross Weight: 72 lbs (32.7 kg) Net Weight: 39 lbs (17.7 kg) Available Color: Black front & silver body
Operating Environment	Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super H13SSH
Chassis	CSE-HS219-R1K63P-A